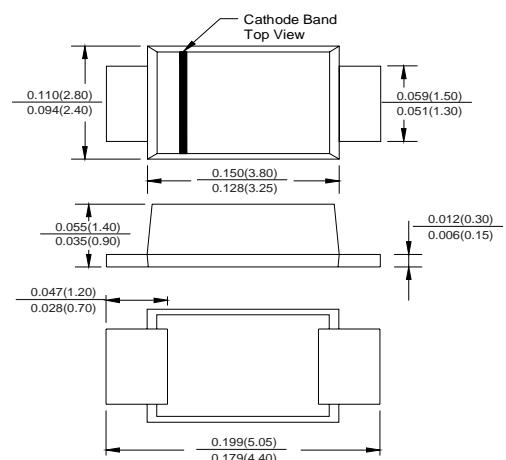


FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives



SMAF



Dimensions in inches and (millimeters)

MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg 0.00086oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	S2AF	S2BF	S2DF	S2GF	S2JF	S2KF	S2MF	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at Ta = 65 °C	I _{F(AV)}	2							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	60							A
Maximum Instantaneous Forward Voltage at 2 A	V _F	1.1							V
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I _R	1 125							µA
Typical Junction Capacitance ¹⁾	C _j	30							pF
Typical Thermal Resistance ²⁾	R _{θJA}	16							°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150							°C

1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

2) Thermal resistance from junction to ambient at 0.375" (9.5 mm) lead length, P.C.B. mounted

Fig.1 Forward Current Derating Curve

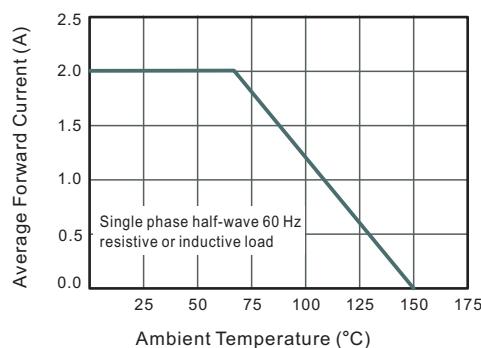


Fig.2 Typical Instantaneous Reverse Characteristics

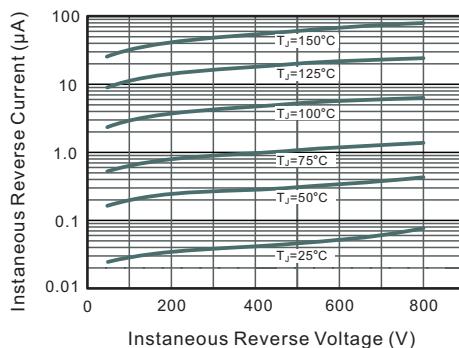


Fig.3 Typical Forward Characteristic

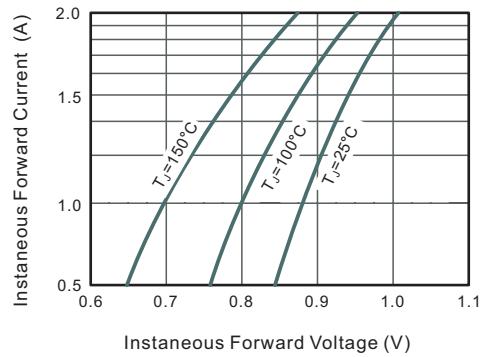


Fig.4 Typical Junction Capacitance

